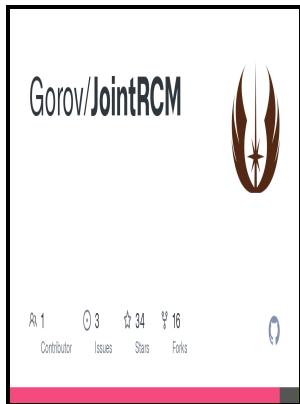


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## Obsolescence and Life Cycle Management For Avionics

Obsolescence is an inevitable occurrence; therefore, the goal of obsolescence and lifecycle management is to minimize the recurring cost impacts and the disruption of supply to customers while maintaining continued airworthiness and regulatory compliance.

## Jet Vapor Deposition: A New,Low Cost Metallization Process

Aerospace has a continual demand for technological progress in aircraft system capabilities and safety improvements, but on a much longer timescale than the technology turnover timescale of the supply base. The report describes the extant research on numerical methods for obsolescence risk assessment and related economic modeling, and provides recommendations for further public guidance and standards that would assist industry and users in adapting to a dynamic environment. Finally, the report suggests some relevant research topics that are not well addressed presently and should be considered for future work.

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Obsolescence and obsolescence management of avionics products are a technically challenging and costly financial problem with many adverse business impacts for both the avionics suppliers and their customers. Effect of Mechanical Shock and Vibration on the Second-level Temperature Cycling Reliability of Ceramic Ball Grid Arrays with a Continuous Compressive Load Applied Dolbear, T.

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The findings and conclusions in this report are those of the author s and do not necessarily represent the views of the funding agency. The report suggests some industry and regulatory practices that could promote best practices; reduce costs and inconvenience; and improve t he product life-cycle pla rning process.

## **Obsolescence and Life Cycle Management For Avionics**

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